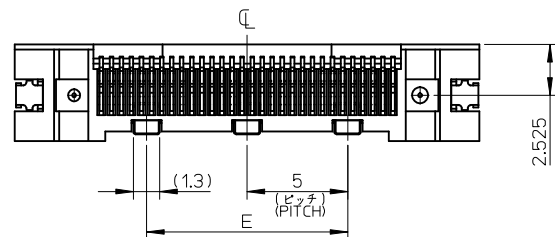
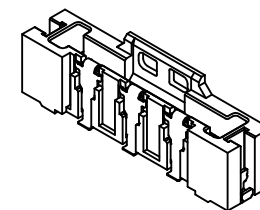
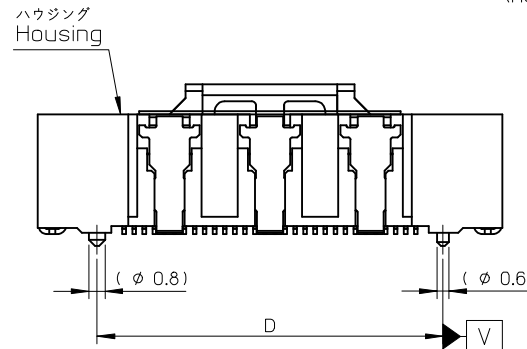
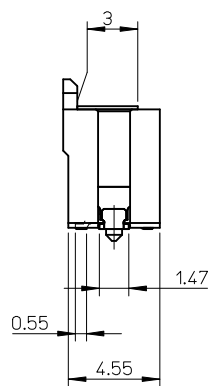
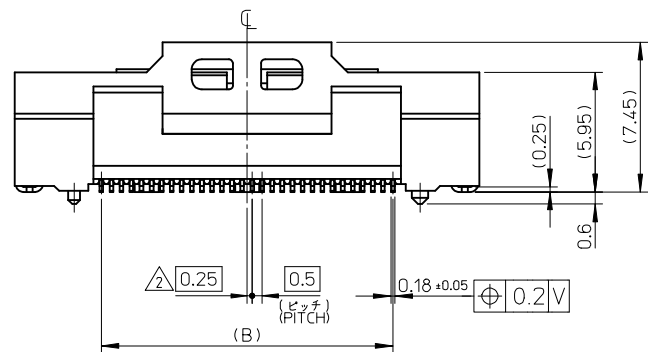


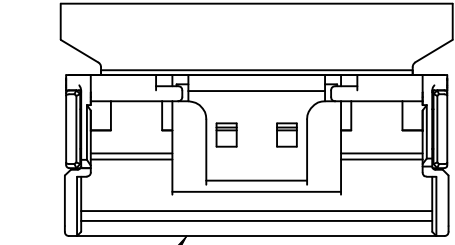
参考基板レイアウト
P.C. BOARD PATTERN
DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)



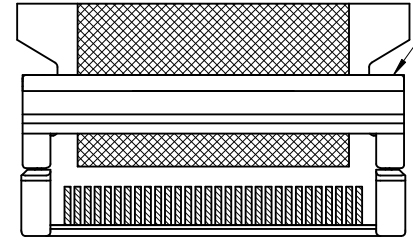
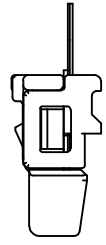
3	10	17.2	19.1	14.5	23.1	501786-3091	30
QTY of Ground Term	E	D	C	B	A	EMBOSSED TAPE PKG.	極数 CIRCUIT
						ORDER No. オーダー番号	

CONNECTOR SERIES No. 501786-***31

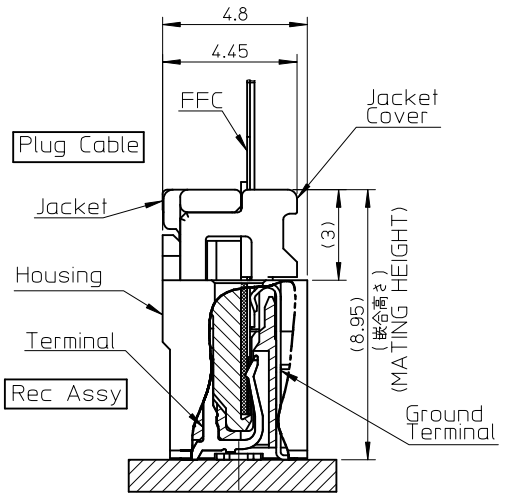
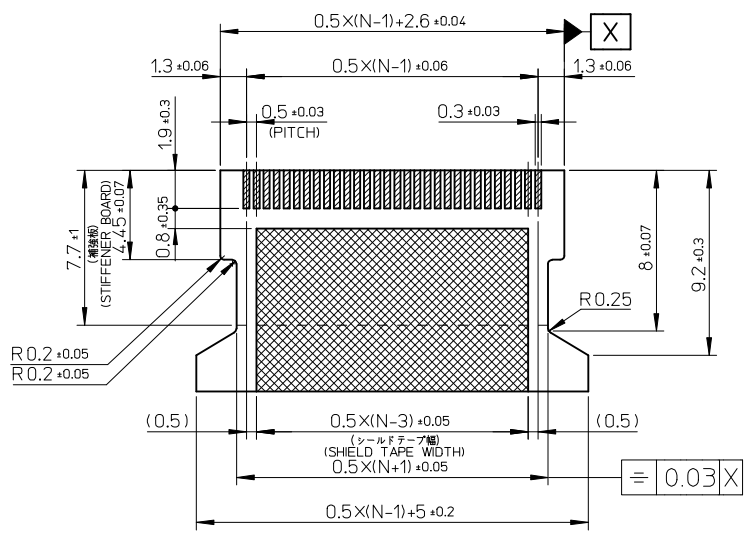
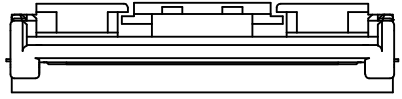
REVISED EC NO: J2010-0779 DRWN: NITISHI 2009/10/19 CHKD: MATSUURA 2009/10/19 APPR: MORIKAWA 2009/10/19	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER ±0.2	DRAWN BY H. IJIMA	DATE 07/12/25	TITLE 0.5 FFC TO BOARD CONN REC HSG ASSY(ST)		
	10 OVER 30 UNDER ±0.25	CHECKED BY K. MORIKAWA	DATE 07/12/25	MOLEX INCORPORATED		
	30 OVER ±0.3	APPROVED BY H. HIRATA	DATE 07/12/25	DOCUMENT NO. SD-501786-008	SHEET NO. 1 OF 2	
ANGULAR ±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE CHART	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



④ ジャケット JACKET



⑤ ジャケットカバー JACKET COVER



嵌合断面図 MATED CONNECTOR SECTION

注記 NOTE

1. 使用材料 MATERIAL
 - ハウジング HOUSING : 液晶ポリマー (LCP), ガラス充填, UL 94V-0 色: 黒色
 - ターミナル TERMINAL : 燐青銅 (t=0.18)
 - メッキ PLATING : 燐青銅 (t=0.18)
 - CONTACT AREA : ニッケル下地 (1.0 μm 以上) 金メッキ (0.1 μm 以上) OVER NICKEL PLATING (1.0 μm MINIMUM) GOLD PLATING (0.1 μm MINIMUM)
 - ソルダーテール SOLDER TAIL : ニッケル下地 金メッキ
 - TAIL AREA : OVER NICKEL PLATING GOLD PLATING
 - 金具 FITTING NAIL : 燐青銅 (t=0.25)
 - グラウンド端子 GROUND TERMINAL : ニッケル下地 錫メッキ (1.0 μm 以上) PHOSPHOR BRONZE (t=0.15) TIN OVER NICKEL PLATING (1.0 μm MINIMUM)

- N=偶数に適用 (N:極数) APPLY FOR N-EVEN(CIRCUIT)
- ③ パターン剥離止め用金具 FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B PATTERN.
 - ④ 適合ジャケット: 501783-**09 製品詳細寸法はSD-501783-004を参照下さい。 RE DETAILED DIMENTION,SEE SD-501783-004.
 - ⑤ 適合ジャケットカバー: 501784-**08. 製品詳細寸法はSD-501784-005を参照下さい。 APPLICABLE JACKET COVER: 501784-**08. RE DETAILED DIMENTION SEE SD-501784-005
6. ELV及びRoHS適合品 ELV AND RoHS COMPLIANT
 7. FFCについて ABOUT FFC
 打ち抜き方向は導体側から補強板側を推奨します。 導体部については軟烙銅35 μmまたは50 μmを推奨します。
 RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER SIDE
 RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL
 RECOMMENDED CONDUCTOR THICKNESS: 35MICROMETER OR 50MICROMETER

コネクタ接点部 CONTACT AREA
 シールド部 SHIELD AREA

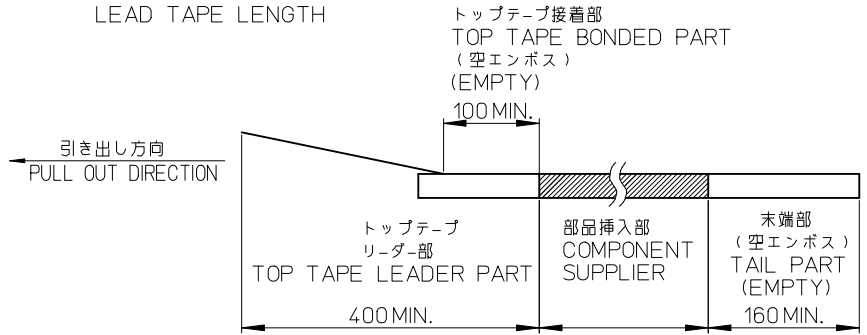
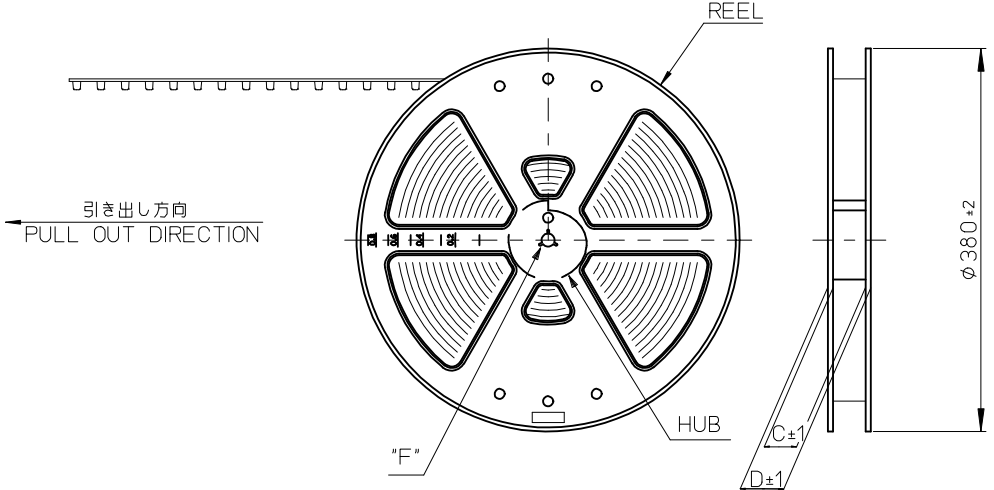
適合する金めっきFFC推奨寸法
 APPLICABLE FFC OF GOLD PLATING RECOMMENDED DIMENSION
 (仕上がり厚さ: コネクタ接点部 0.3±0.03) シールド部 0.44±0.05)
 (THICKNESS :CONTACT AREA 0.3±0.03) SHIELD AREA 0.44±0.05)

REVISED EC NO: J2010-0779 DRAWN: NISHI 2009/10/19 CHKD: NAWATSUURA 2009/10/19 APPR: KIMORI KAWA 2009/10/19	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION		
				MM ONLY		≠	METRIC			
		10 UNDER	± 0.2	DRAWN BY	DATE	TITLE				
		10 OVER 30 UNDER	± 0.25	H. IJIMA	07/12/25	0.5 FFC TO BOARD CONN REC HSG ASSY(ST)				
		30 OVER	± 0.3	CHECKED BY	DATE					
		ANGULAR ±1 °		K. MORIKAWA	07/12/25					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE					
				H. HIRATA	07/12/25	MOLEX INCORPORATED				
				MATERIAL NO.	DOCUMENT NO.	SEE SHEET 1			SHEET NO.	
				SD-501786-008					2 OF 2	
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

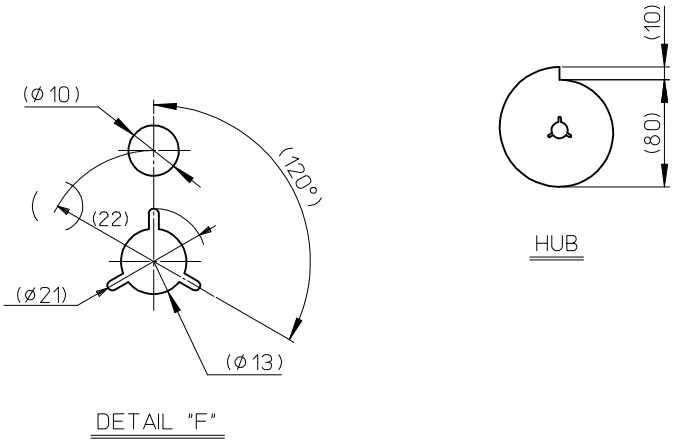
ELV AND RoHS COMPLIANT.

NOTES

1. 梱包数量：900 個/リール
NUMBER OF CONNECTORS:900 PCS/REEL
2. リードテープ長さ
LEAD TAPE LENGTH



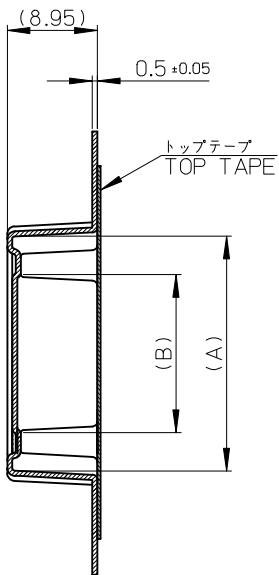
3. 製品詳細寸法については図面 SD-501786-008を参照下さい。
RE DETAILED DIMENSION, SEE SD-501786-008.
4. 材料(MATERIAL)
キャリアテープ(CARRIER TAPE)：ポリスチレン(POLYSTYRENE)
トップテープ(TOP TAPE)：PET, PE, PE
リール(REEL)：ポリスチレン(POLYSTYRENE)<リサイクル材を含む>
<RECYCLE MATERIAL CONTAINED>
5. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT



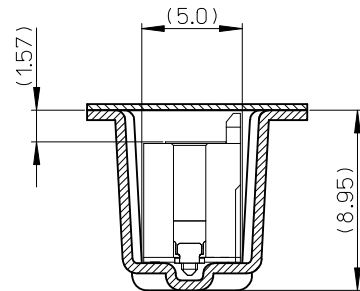
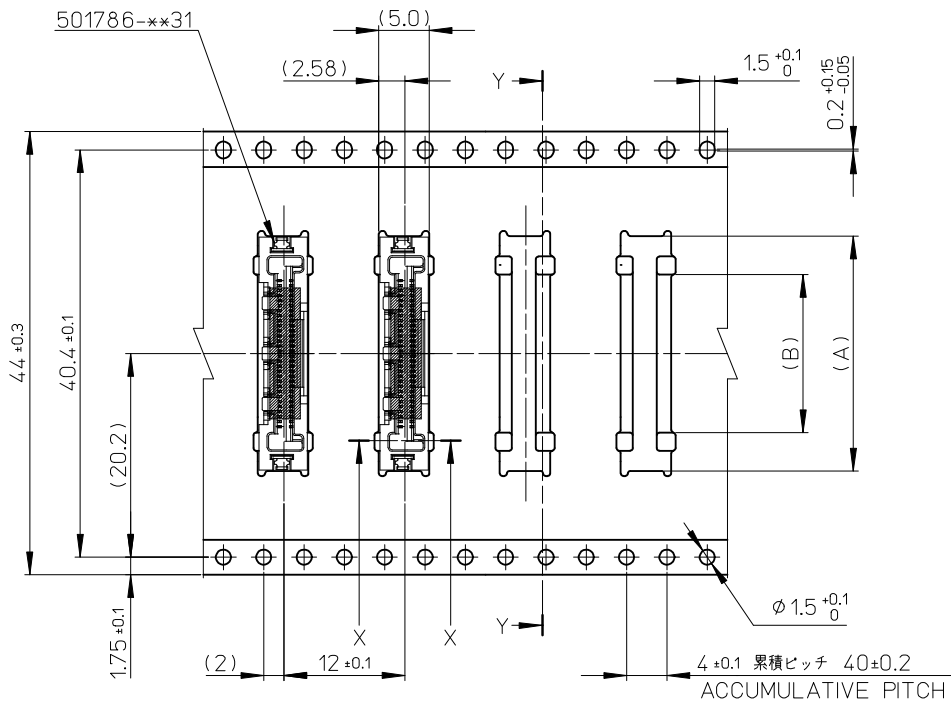
501786-**91 MODEL NO.

REVISED EC NO: J2009-1986 DRWN: YSHIBATA 2009/02/26 CHKD: THARUYAMA 2009/02/26 APPR: NUKITA 2009/02/26 REV: A	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE			
	10 OVER 30 UNDER	±0.25	H. IJIMA	07/12/25	EMBSTP PKG FOR 0.5 FFC TO BOARD ST TYPE			
	30 OVER	±0.3	CHECKED BY	DATE	MOLEX INCORPORATED			
	ANGULAR	±3 °	K. MORIKAWA	07/12/25	MATERIAL NO. 501786-**91			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	DOCUMENT NO.		SHEET NO.		
		H. HIRATA	07/12/25	SD-501786-009		1 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								

引き出し方向
PULL OUT DIRECTION



SECT. Y-Y



SECT. X-X

44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE

56	61.4	57.4	25.68	33.3	501786-5091	50
44	49.4	45.4	15.68	23.3	501786-3091	30
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	製品番号 MATERIAL NO.	極数 CKT

REVISED EC NO: J2009-1986 DRWN: YSHIBATA 2009/02/26 CHKD: THARUYAMA 2009/02/26 APPR: NUKITA 2009/02/26 REV A	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		10 UNDER ±0.2	DRAWN BY H. IJIMA	DATE 07/12/25	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD ST TYPE	
		10 OVER 30 UNDER ±0.25	CHECKED BY K. MORIKAWA	DATE 07/12/25	MOLEX INCORPORATED	
		30 OVER ±0.3	APPROVED BY H. HIRATA	DATE 07/12/25	MATERIAL NO. 501786-**91	DOCUMENT NO. SD-501786-009
		ANGULAR ±3°	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				